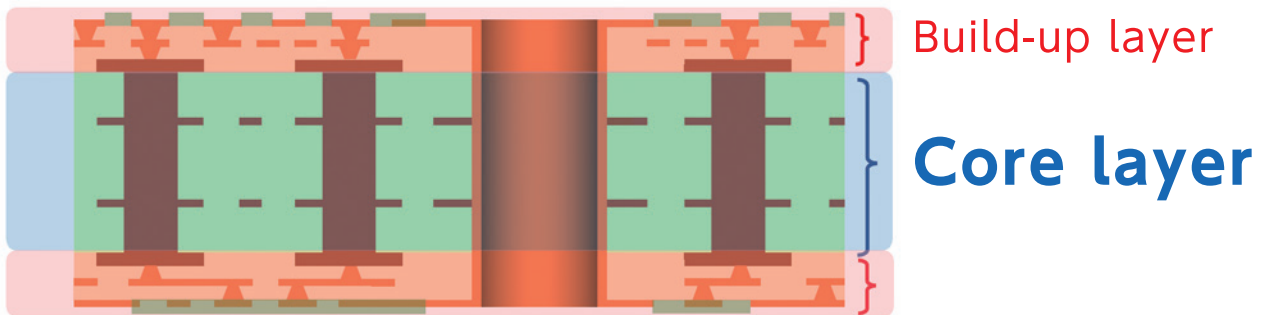


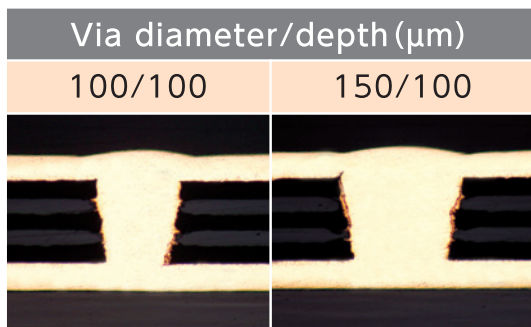
TOP LUCINA GAP

Additives for acid copper plating to large-diameter via holes

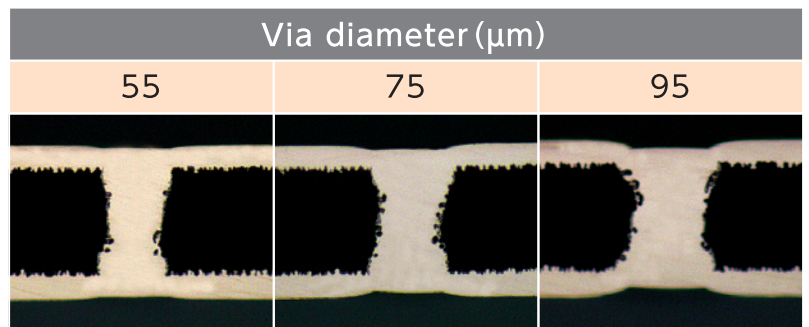
- For core layers to achieve high through-hole filling performance
- Excellent in filling performance for large-diameter via holes
- Regardless of pattern size, uniform thickness is available



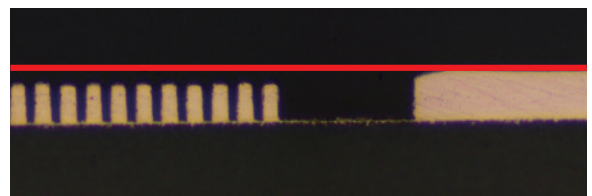
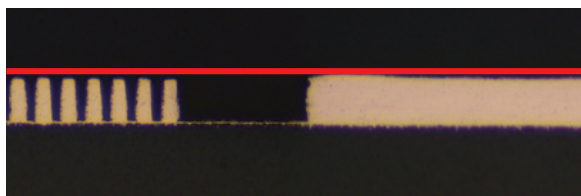
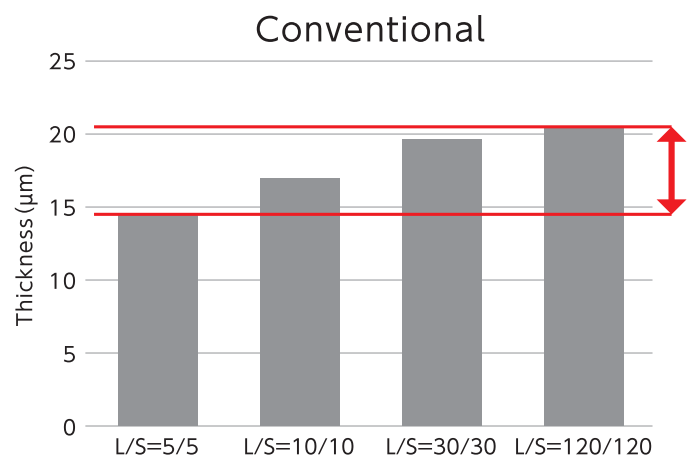
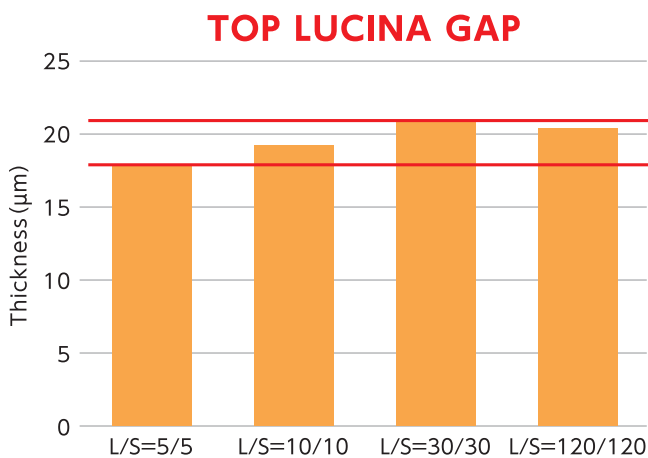
For large-diameter via



For through-hole filling



Reduce thickness variation, freely draw fine patterns



Surface thickness 18μm